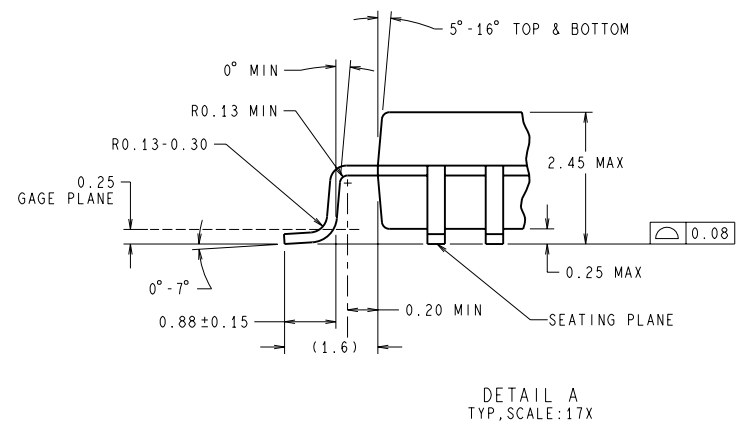


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
C	REVISE AND REDRAW PER JEDEC MS-022.	11041	07/12/95	DEG/



DETAIL A
TYP, SCALE: 17X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON ALLOY 42/COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.15 mm.
- REFERENCE JEDEC STANDARD MS-022, VARIATION BA,
DATED FEB/95.

APPROVALS		DATE	 2900 Semiconductor dr, Santa Clara, CA 95052-8090		
DRAWN	<i>D.E. Grady</i>	07/12/95			
DFTG. CHK.			PQFP, JEDEC METRIC, (S), 14 X 14 X 2.0mm, 52 LEAD		
ENGR. CHK.					
 PROJECTION INCH (MM)		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-VJM52A	C
DO NOT SCALE DRAWING				SHEET 1 of 1	